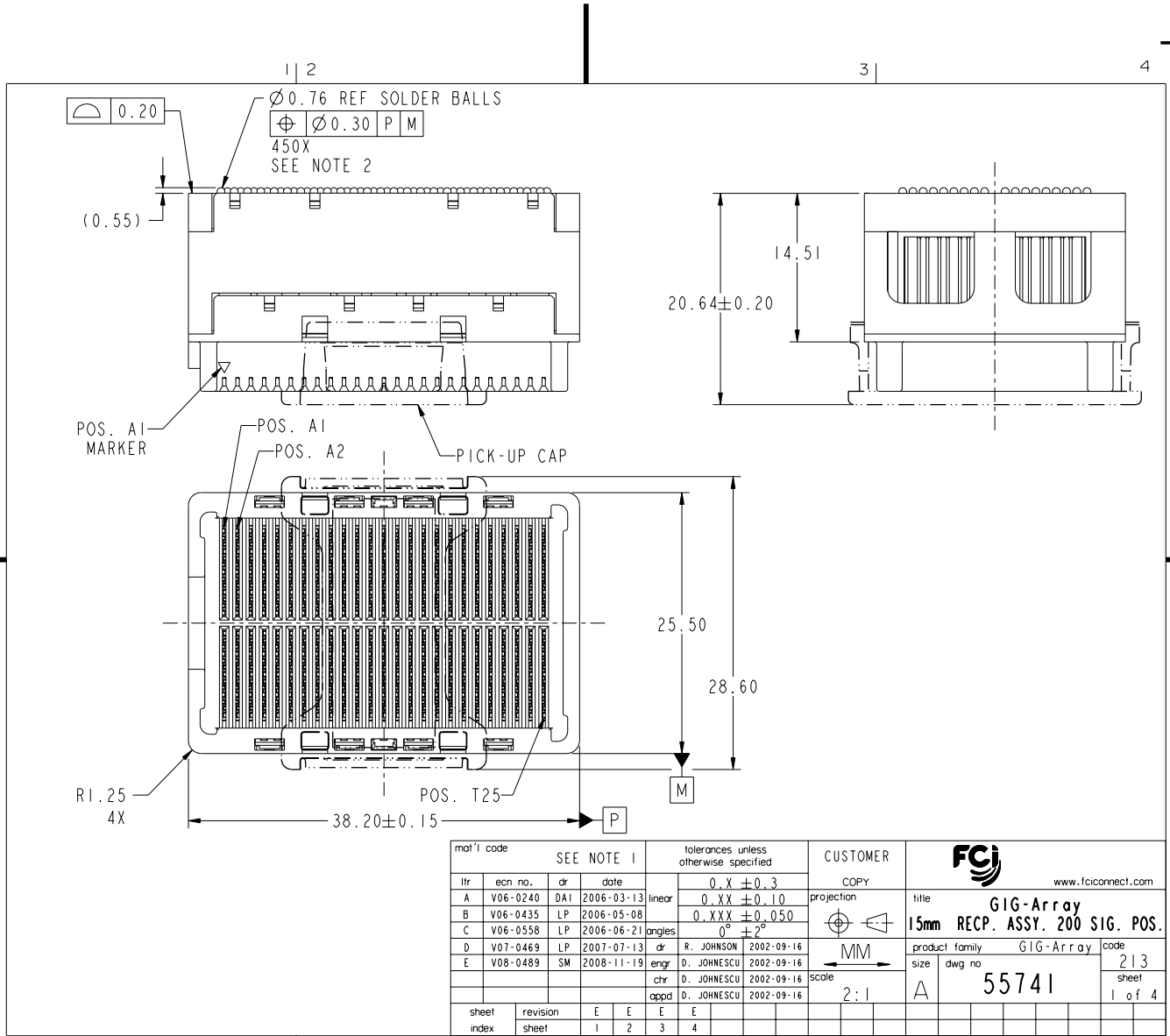




This document is the property of and embodies CONFIDENTIAL INFORMATION of FCI. No part of the information shown on this document may be used in any way or disclosed to others without the written consent of FCI. Copyright FCI.



mat'l code		SEE NOTE 1		tolerances unless otherwise specified		CUSTOMER		FCI	
ltr	ecn no.	dr	date	linear	0.X ± 0.3	COPY		www.fciconnect.com	
A	V06-0240	DAI	2006-03-13	linear	0.XX ± 0.10	projection		GIG-Array	
B	V06-0435	LP	2006-05-08	angles	0.XXX ± 0.050	MM		15mm RECP. ASSY. 200 SIG. POS.	
C	V06-0558	LP	2006-06-21	angles	0° ± 2°	scale		product family GIG-Array code 213	
D	V07-0469	LP	2007-07-13	chr	R. JOHNSCU 2002-09-16	2:1		size dwg no 55741 sheet 1 of 4	
E	V08-0489	SM	2008-11-19	appd	D. JOHNSCU 2002-09-16			cage code 22526	
sheet index	revision sheet	E	E	E	E			STATUS: Released Printed: Sep 03, 2010	
		1	2	3	4				

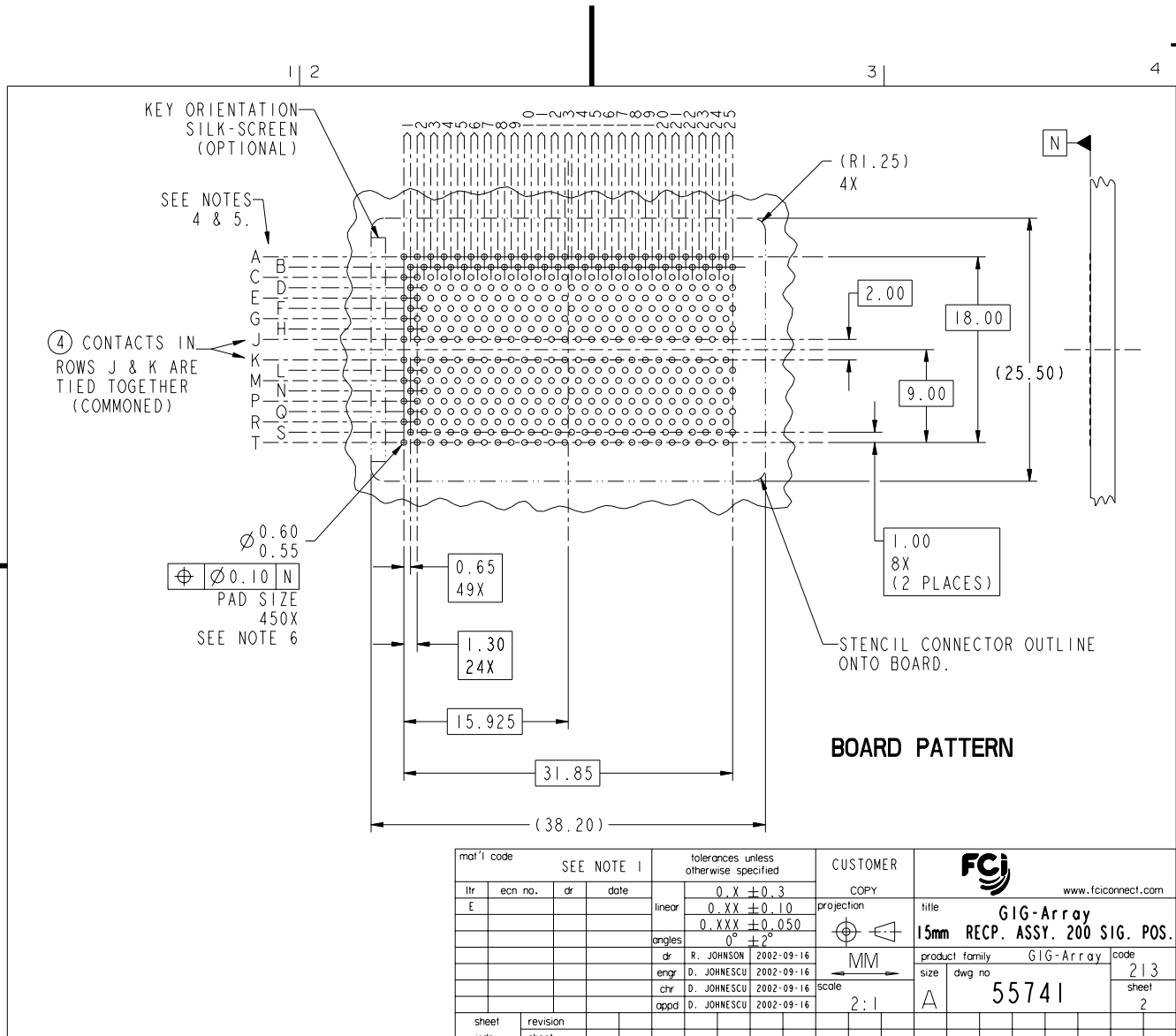
Pro/E

PDM: Rev:E

STATUS: Released Printed: Sep 03, 2010



This document is the property of, and embodies  
 CONFIDENTIAL INFORMATION of FCJ.  
 No part of the information shown on this  
 document may be used in any way or disclosed  
 to others without the written consent of FCJ.  
 Copyright FCJ.

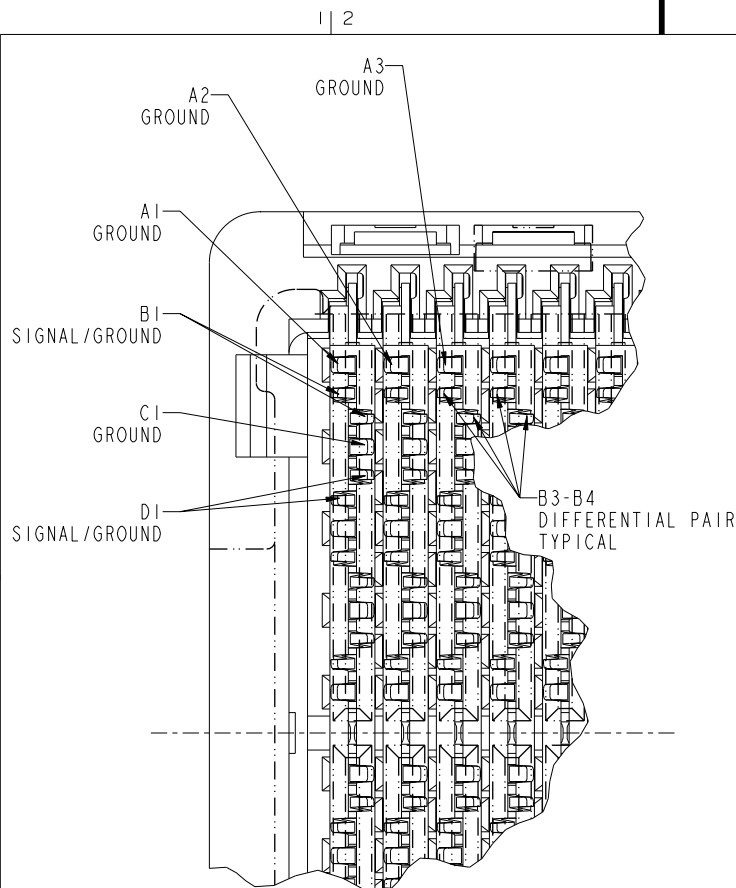


**BOARD PATTERN**

mat'l code		SEE NOTE 1		tolerances unless otherwise specified		CUSTOMER		www.fcjconnect.com	
itr	ecm no.	dr	date	linear	0.X ± 0.3	COPY		title	
E					0.XX ± 0.10			15mm GIG-Array	
				angles	0.XXX ± 0.050			RECP. ASSY. 200 SIG. POS.	
				dr	0° ± 2°	scale		product family GIG-Array code	
				engr	R. JOHNSON 2002-09-16	2:1		size dwg no 213	
				chr	D. JOHNESCU 2002-09-16			sheet	
				appd	D. JOHNESCU 2002-09-16			2	
sheet index	revision sheet							cage code 22526	



This document is the property of and embodies  
 CONFIDENTIAL INFORMATION of FCJ.  
 No part of the information shown on this  
 document may be used in any way or disclosed  
 to others without the written consent of FCJ.  
 Copyright FCJ.



**NOTES:**

- ① MATERIAL:  
 HOUSING: LCP  
 CONTACT: COPPER ALLOY  
 PLATING (CONTACT): Au OVER Ni.  
 UL RATING: 94 V-0  
 SOLDER BALL: (SEE TABLE) EUTECTIC  
 SnPb OR LEAD FREE 95.5 Sn/4Ag/0.5Cu.
- ② SOLDER BALLS WILL NOT BE PERFECT  
 SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- ③ MATED HEIGHT EFFECTED BY CUSTOMERS'  
 PCB PAD SIZE, PLATING, SOLDER REFLOW  
 PROFILE & SOLDER PASTE.
- ④ CONTACTS IN ROWS A,C,E,G,J,K,M,P,R AND T  
 ARE SINGLE BEAM CONTACTS,  
 USED AS GROUND PINS.  
 (NOTE: CONTACTS IN ROWS J & K ARE  
 TIED TOGETHER [COMMONED])
- ⑤ CONTACTS IN ROWS B,D,F,H,L,N,Q AND S  
 ARE DUAL BEAM CONTACTS,  
 TYPICALLY USED AS SIGNAL PINS.

**RECEPTACLE INTERFACE  
 DESCRIPTION**

mat'l code		SEE NOTE 1		tolerances unless otherwise specified		CUSTOMER		www.fcjconnect.com	
ltr	ecn no.	dr	date	linear	0.X ± 0.3	COPY		title	
E					0.XX ± 0.10			15mm GIG-Array	
				angles	0.XXX ± 0.050			RECP. ASSY. 200 SIG. POS.	
					0° ± 2°	MM		product family GIG-Array code	
		dr	R. JOHNSON 2002-09-16	engr	D. JOHNESCU 2002-09-16	size		213	
		chr	D. JOHNESCU 2002-09-16	appd	D. JOHNESCU 2002-09-16	scale		sheet	
						7:1		3	
sheet index	revision sheet							3	

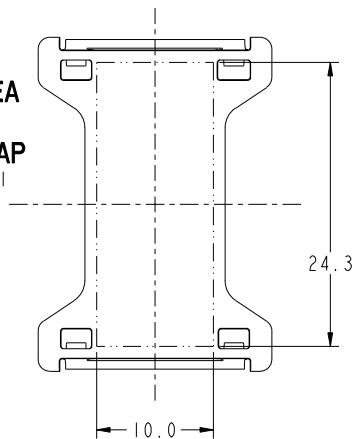
sheet index    revision sheet    Pro/E    PDM: Rev:E    STATUS: Released    cage code 22526    Printed: Sep\_03\_2010



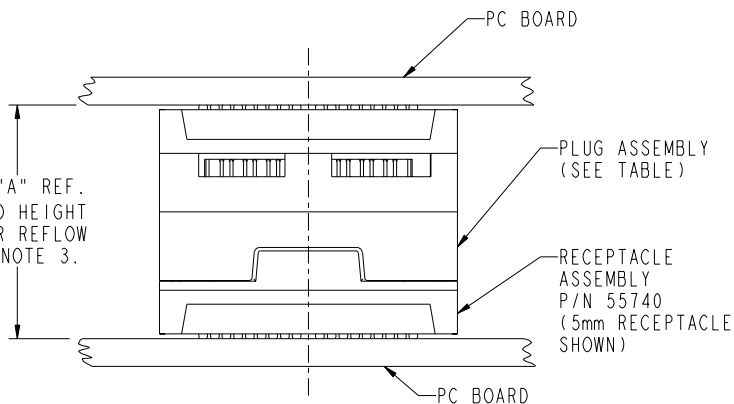
This document is the property of and embodies  
 CONFIDENTIAL INFORMATION of FCI.  
 No part of the information shown on this  
 document may be used in any way or disclosed  
 to others without the written consent of FCI.  
 Copyright FCI.

PRODUCT NUMBER	SOLDER BALL
55741-001	SnPb
55741-001LF	SnAgCu LEAD FREE ⑦⑧

**FLAT AREA FOR PICK-UP CAP**  
 SCALE 2:1



DIM "A" REF.  
 MATED HEIGHT  
 AFTER REFLOW  
 SEE NOTE 3.



**END VIEW OF MATED CONNECTORS**  
 SCALE 2:1

DIM. "A"	PLUG ASSEMBLY P/N
25	55737
27	10026802
28	10055142
30	55738
35	55739
40	10054783

**NOTES:**

- ⑥ SPECIFIED POSITIONAL TOLERANCE DEFINES PAD TO PAD LOCATION WITHIN LAND PATTERN. POSITIONAL TOLERANCE OF LAND PATTERN TO FUDICIAL MARKS OR PCB DATUMS SHALL BE DEFINED BY CUSTOMER. FOR RECOMMENDED PRODUCT APPLICATION AND PCB DESIGN DETAILS, SEE DOC. NO. GS-20-016.
- ⑦ FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033. LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEADFREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION.
- ⑧ THIS PRODUCT MEETS THE EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008. PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION.

mat'l code		SEE NOTE 1		tolerances unless otherwise specified		CUSTOMER		www.fciconnect.com	
ltr	ecn no.	dr	date	linear	0.X ± 0.3	COPY		title	
E					0.XX ± 0.10	projection		15mm GIG-Array	
				angles	0.XXX ± 0.050			RECP. ASSY. 200 SIG. POS.	
				dr	0° ± 2°			product family GIG-Array code 213	
				enrg	R. JOHNSON 2002-09-16	size		sheet 4	
				chr	D. HARPER 2002-09-16	scale		55741	
				appd	D. JOHNESCU 2002-09-16	2:1		A	
sheet index	revision sheet								

Pro/E

PDM: Rev:E

STATUS: Released

Printed: Sep 03, 2010